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Fig. 1

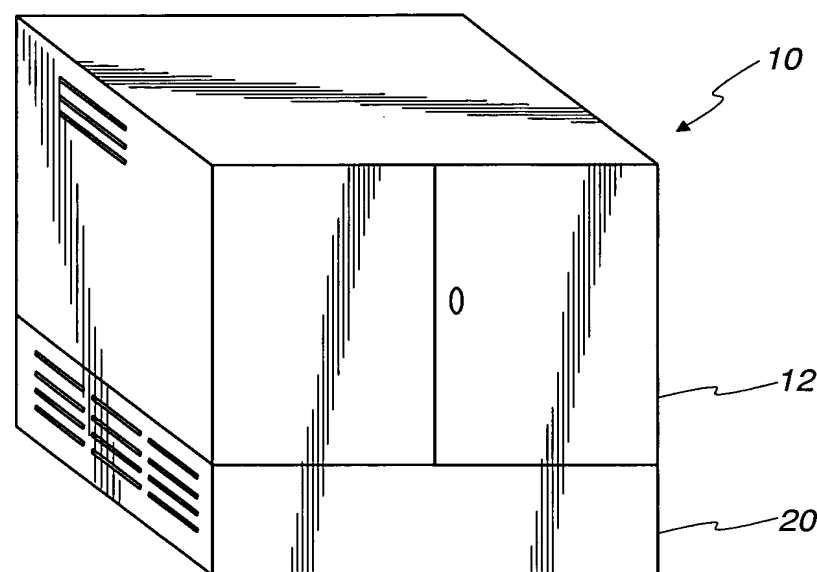


Fig. 2

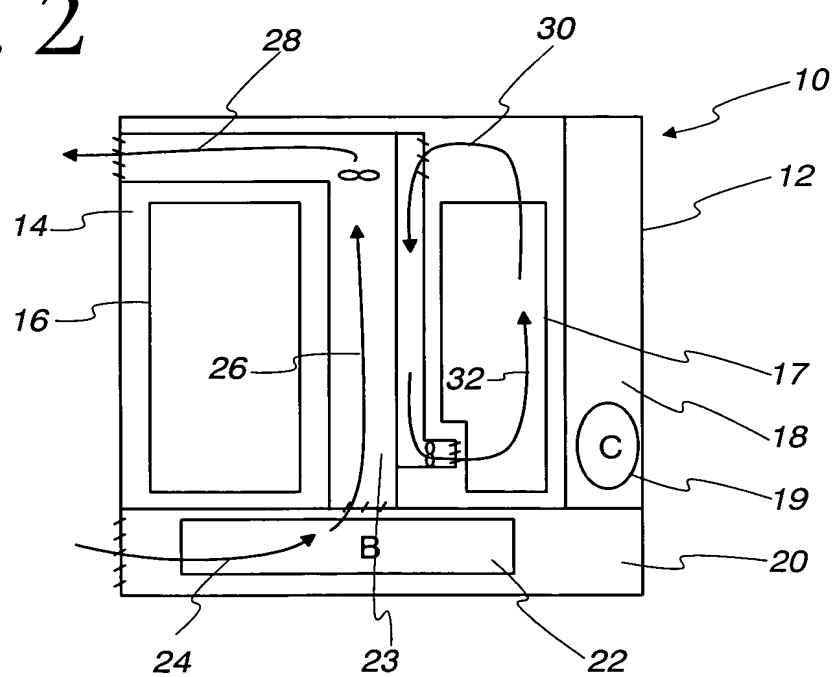


Fig. 3

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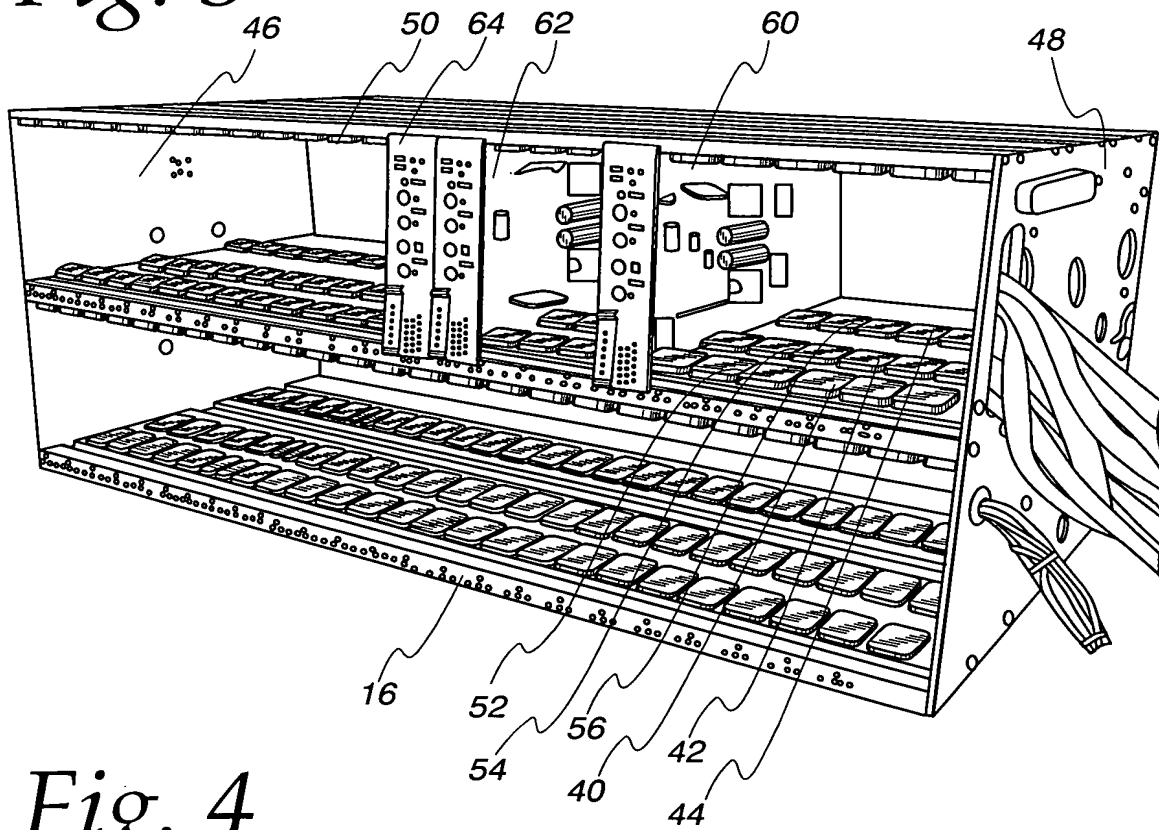
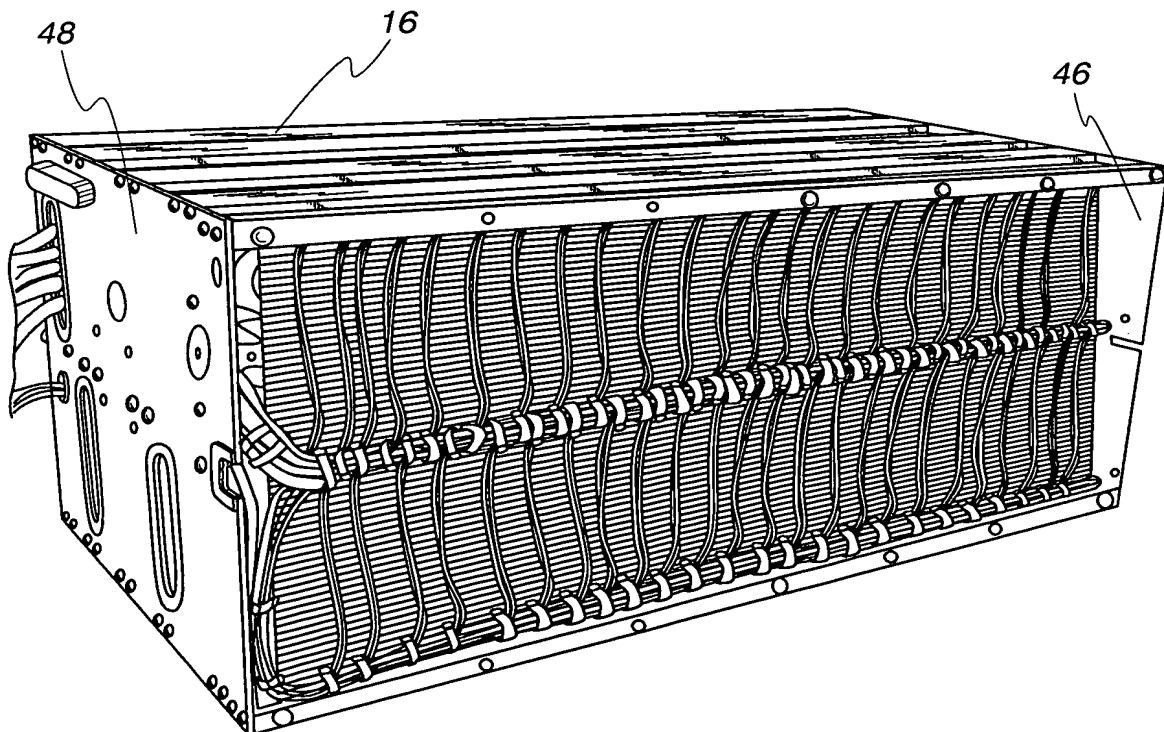
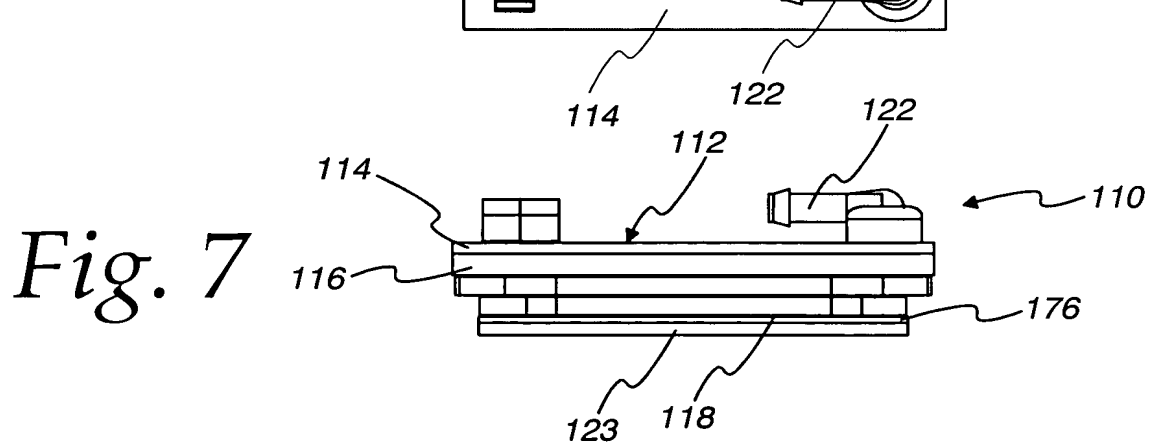
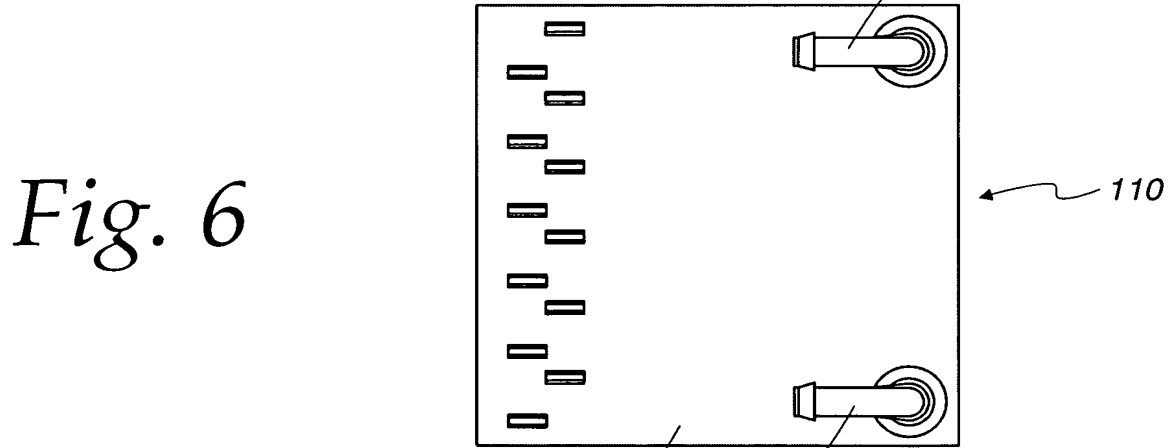
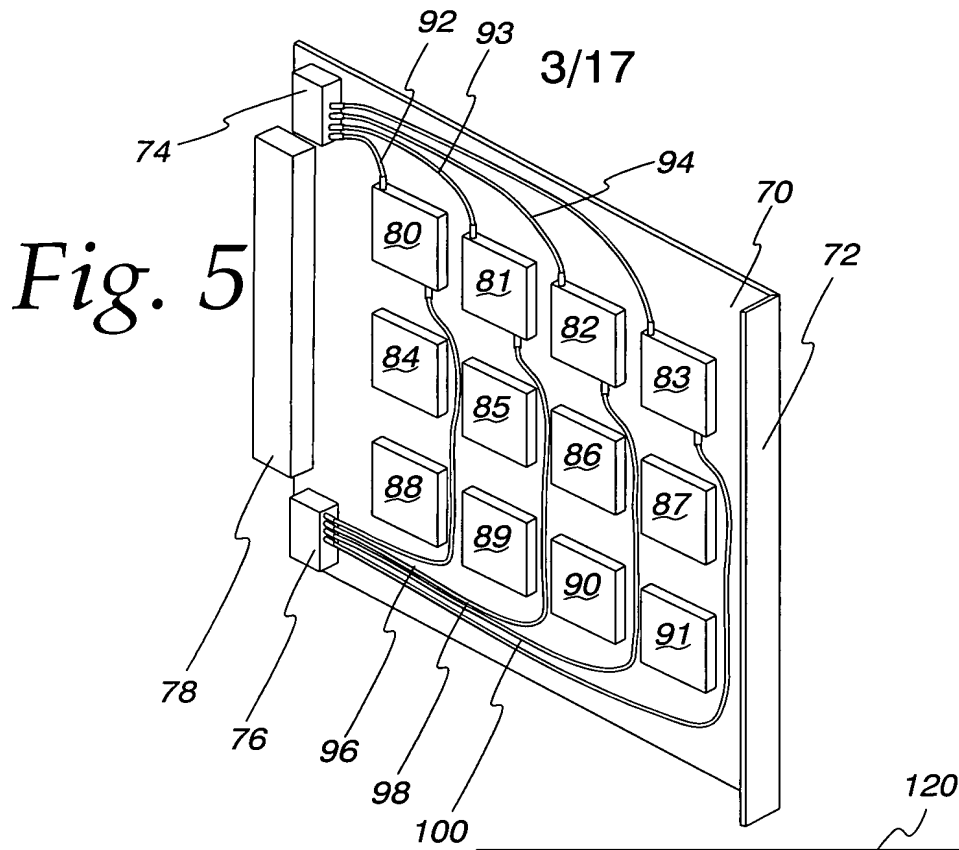


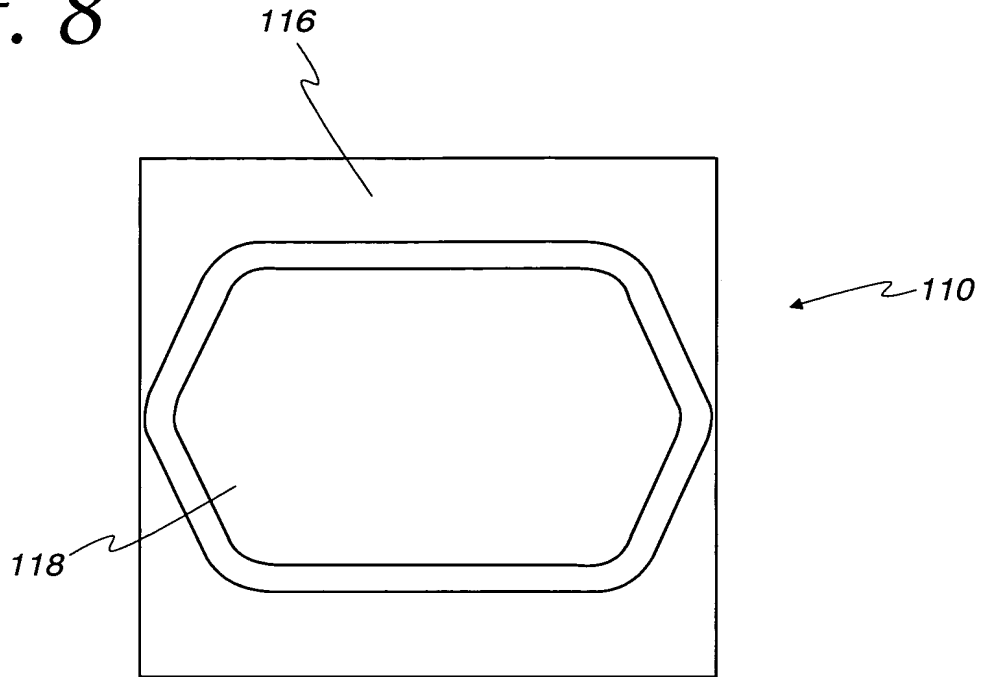
Fig. 4



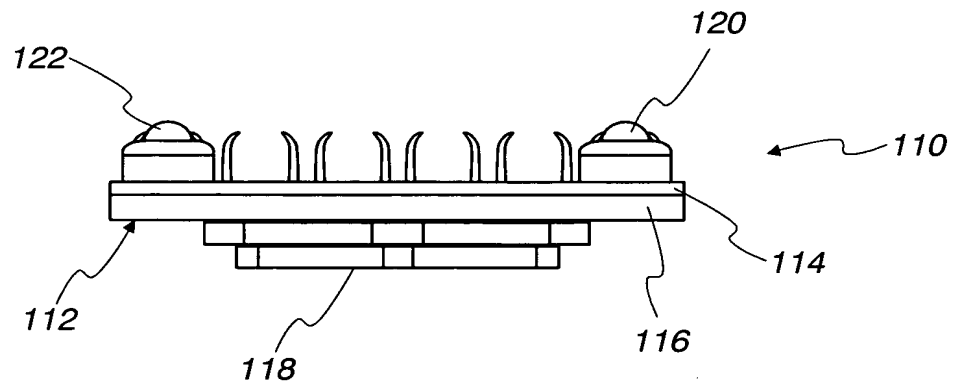


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*Fig. 8* 4/17



*Fig. 9*



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Fig. 10

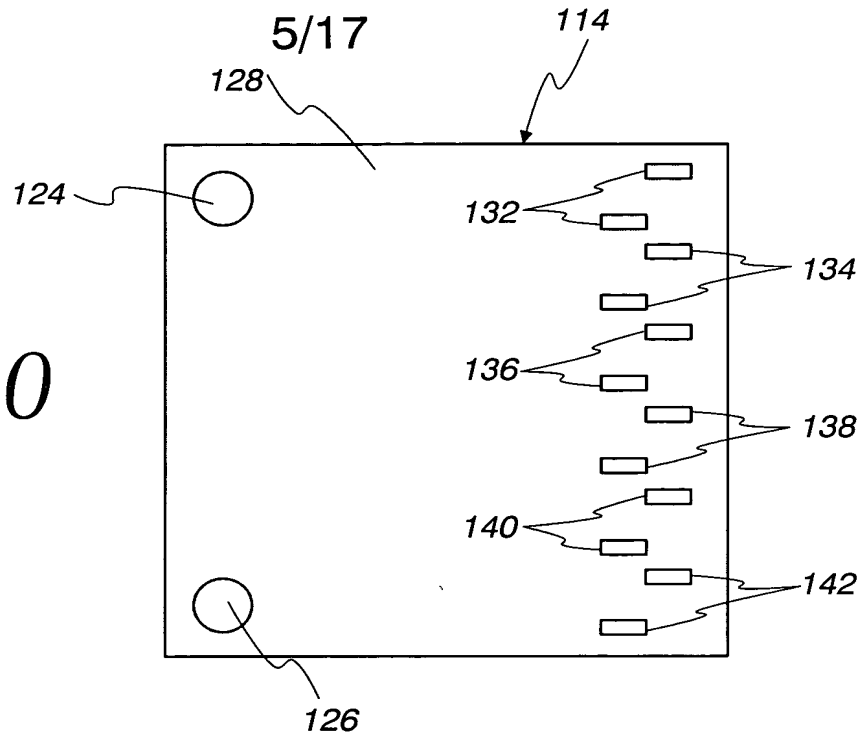


Fig. 11

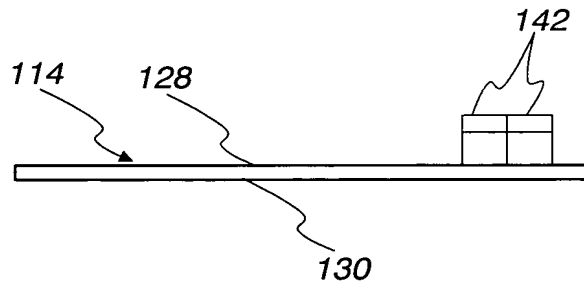
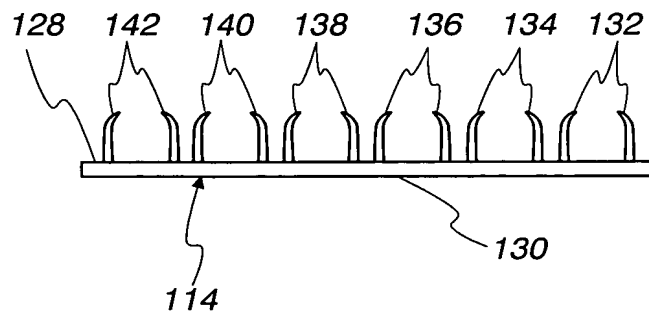
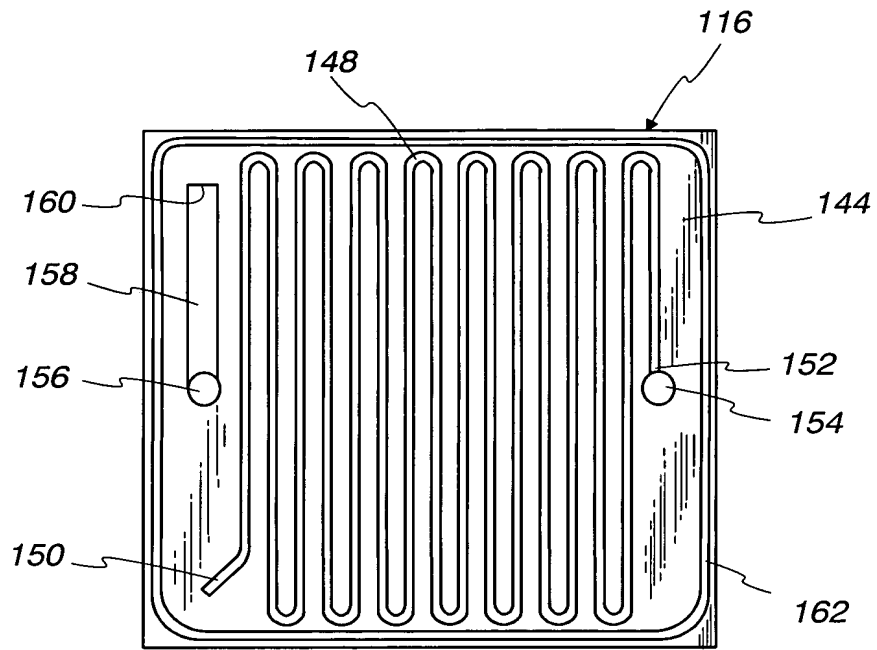


Fig. 12

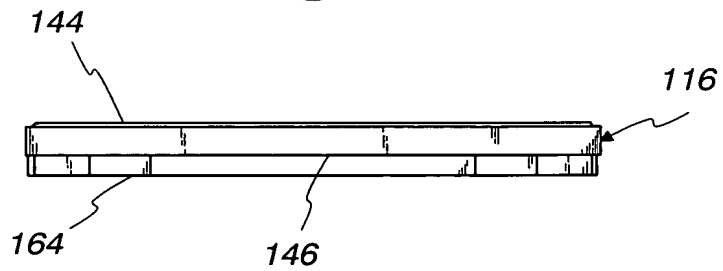


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*Fig. 13*

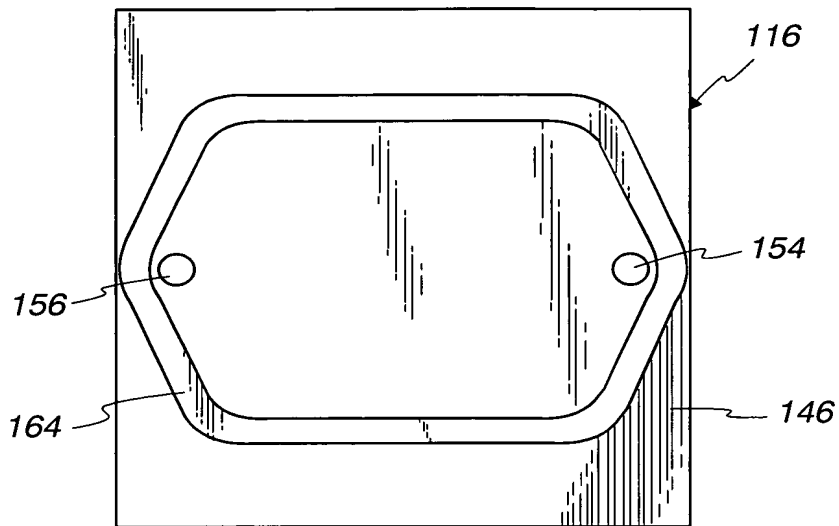


*Fig. 14*

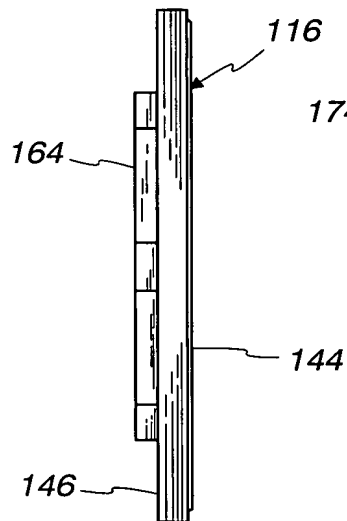


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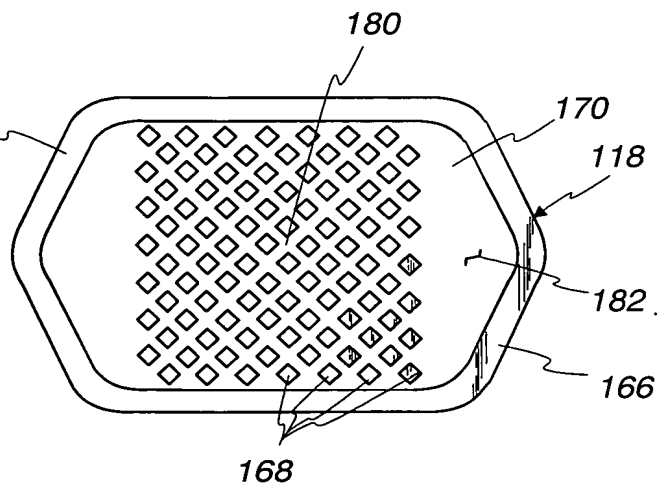
*Fig. 15*



*Fig. 16*

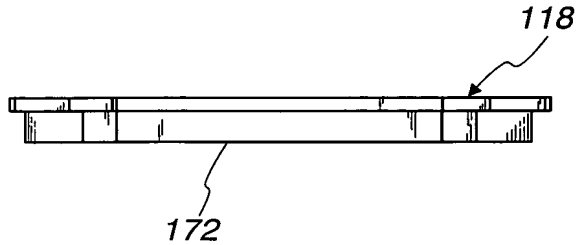


*Fig. 17*

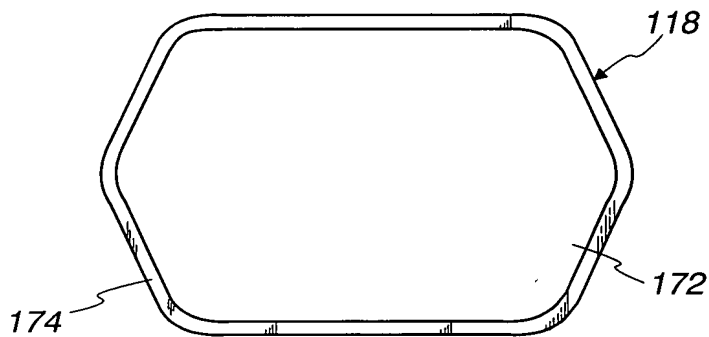


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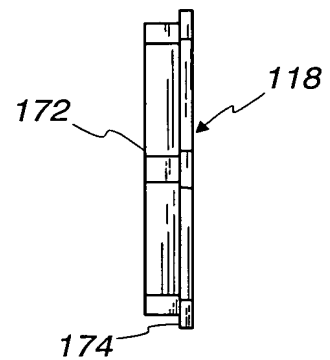
*Fig. 18*



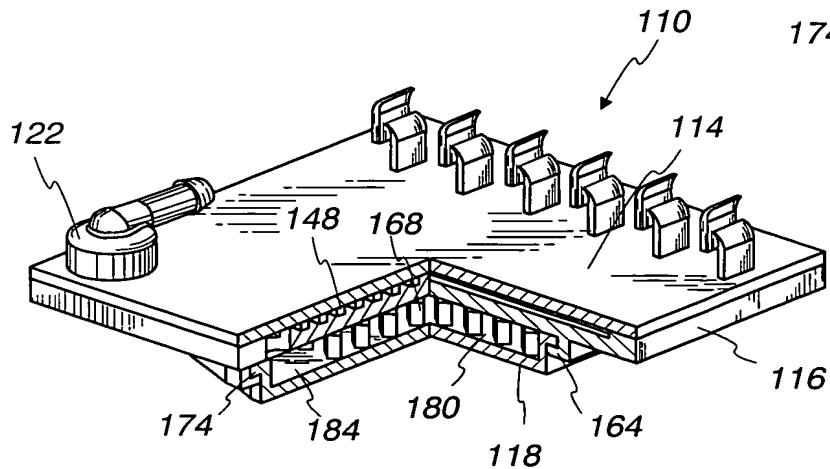
*Fig. 19*



*Fig. 20*



*Fig. 21*



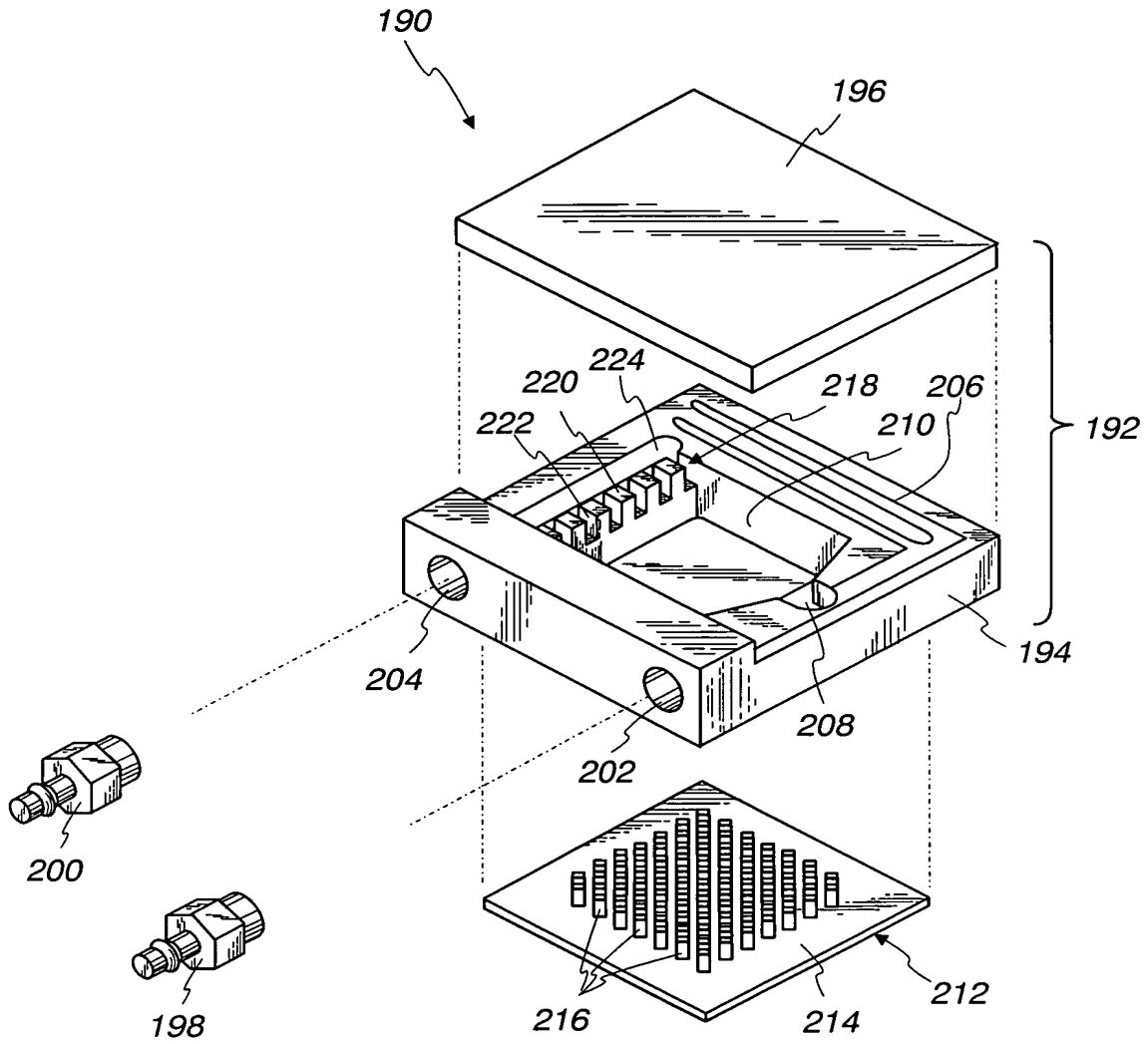


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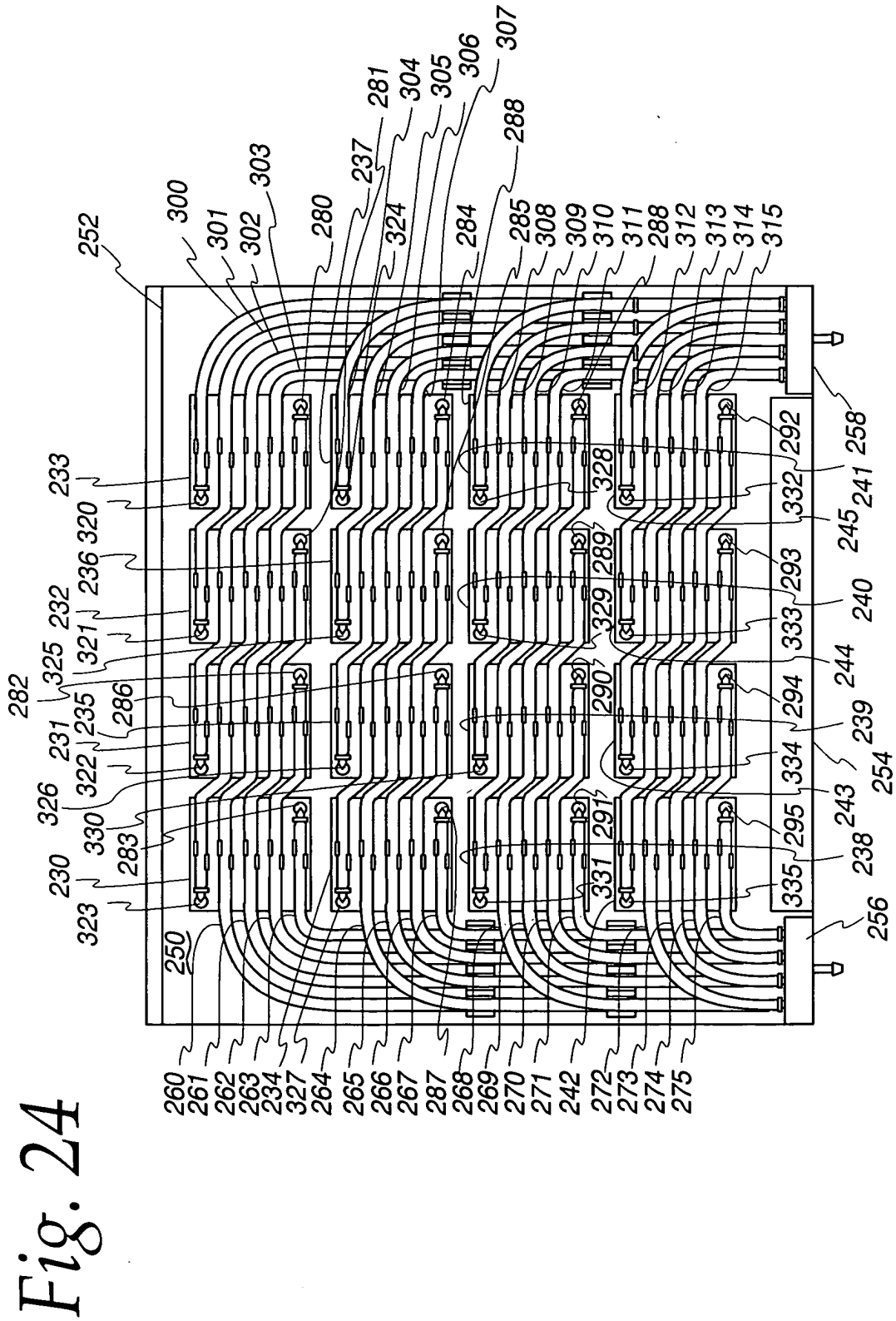
This exploded perspective view illustrates the assembly of a multi-layered electronic device. The components are shown in a disassembled state to reveal their internal structure and alignment. The top layer (114) is a rectangular board with a series of pins (120) along one edge and a circular feature (122) on the opposite side. Below it is a middle layer (116) with a complex, wavy internal pattern (148) and a series of pins (154) along one edge. The bottom layer (118) is a rectangular board with a series of pins (180) along one edge. A separate component (126) is shown with a circular feature (122) and a series of pins (120). A dashed line (124) indicates the alignment of the pins (120) from the top layer (114) and the separate component (126) with the pins (180) on the bottom layer (118). Other labels include 120, 122, 124, 126, 148, 154, 156, 160, 182, 184, and 186.

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*Fig. 23*

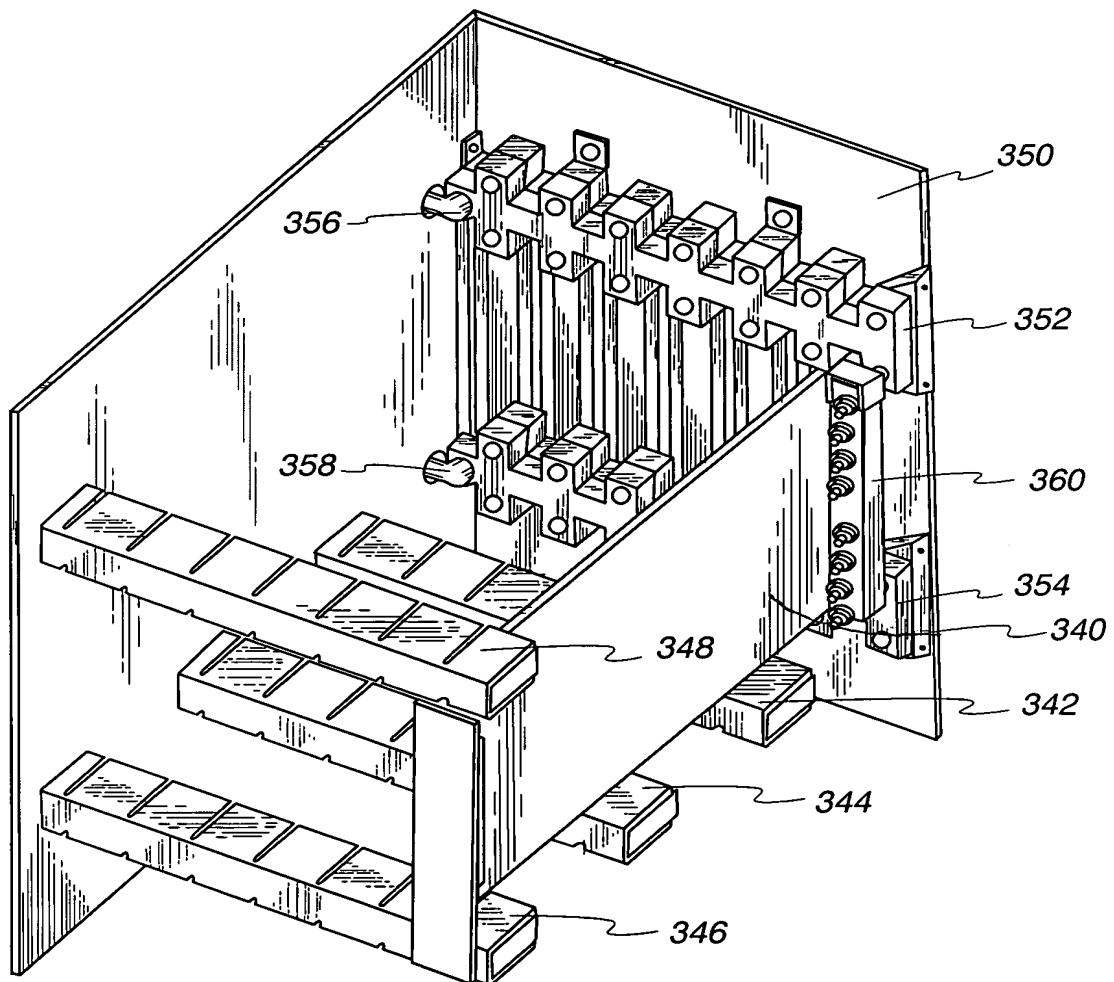


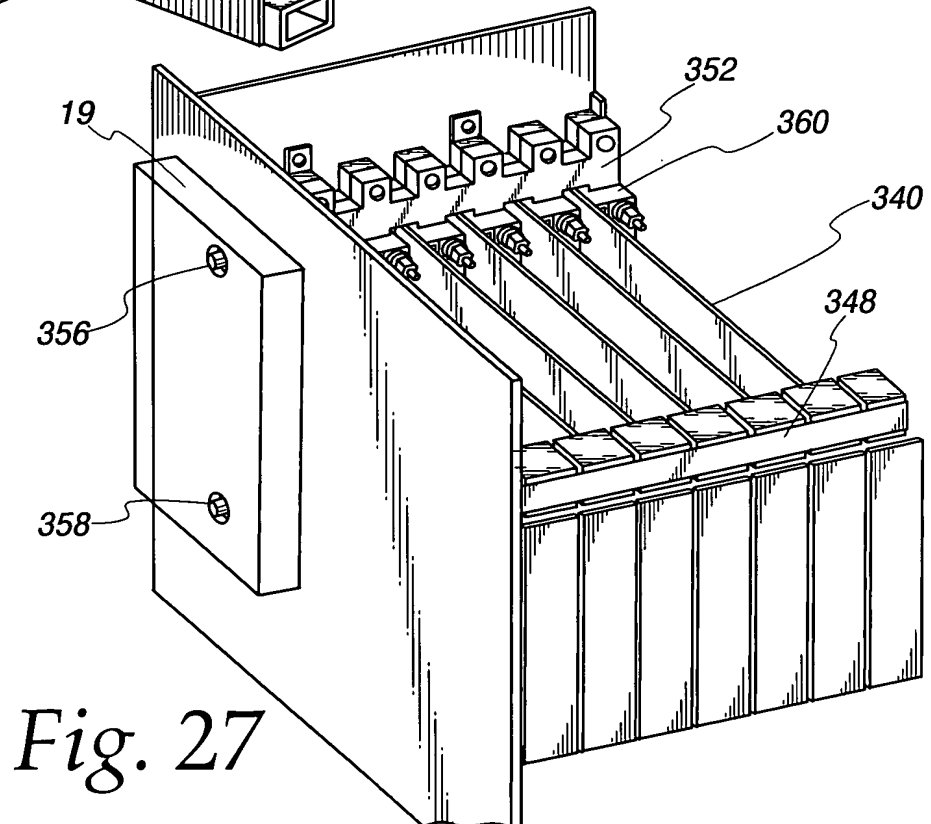
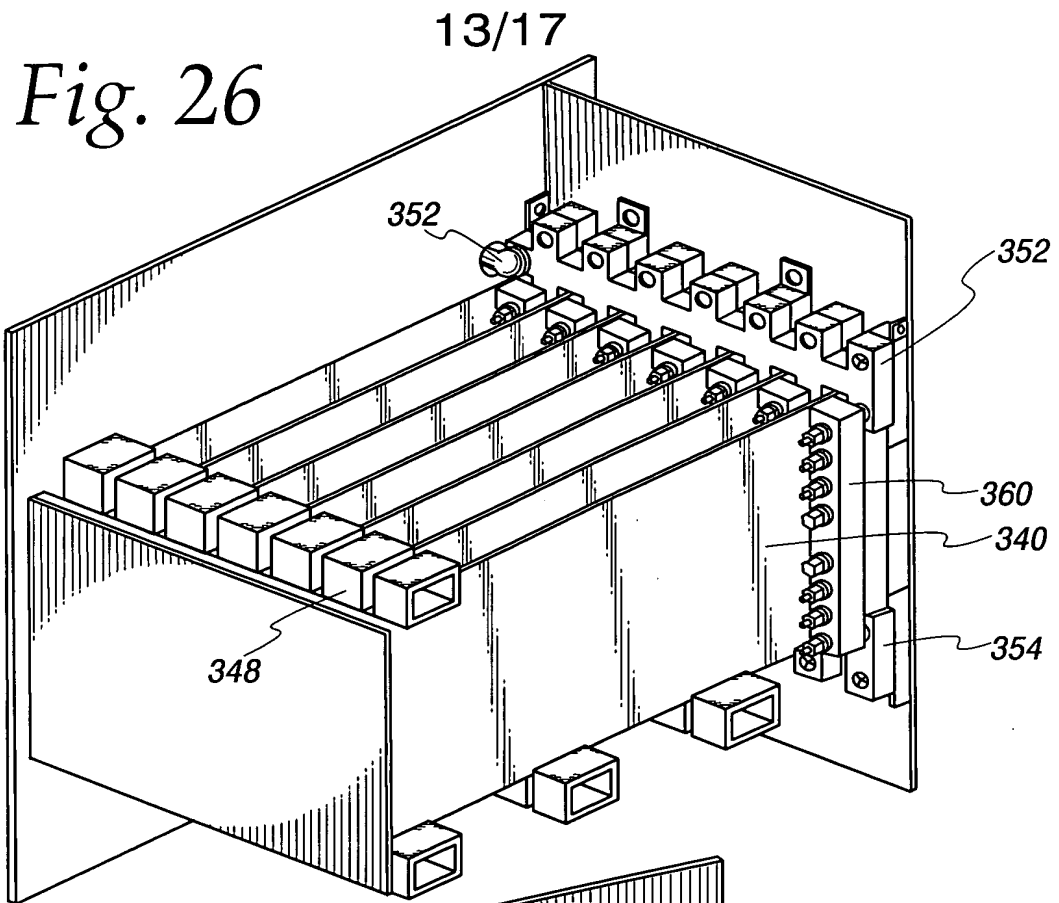
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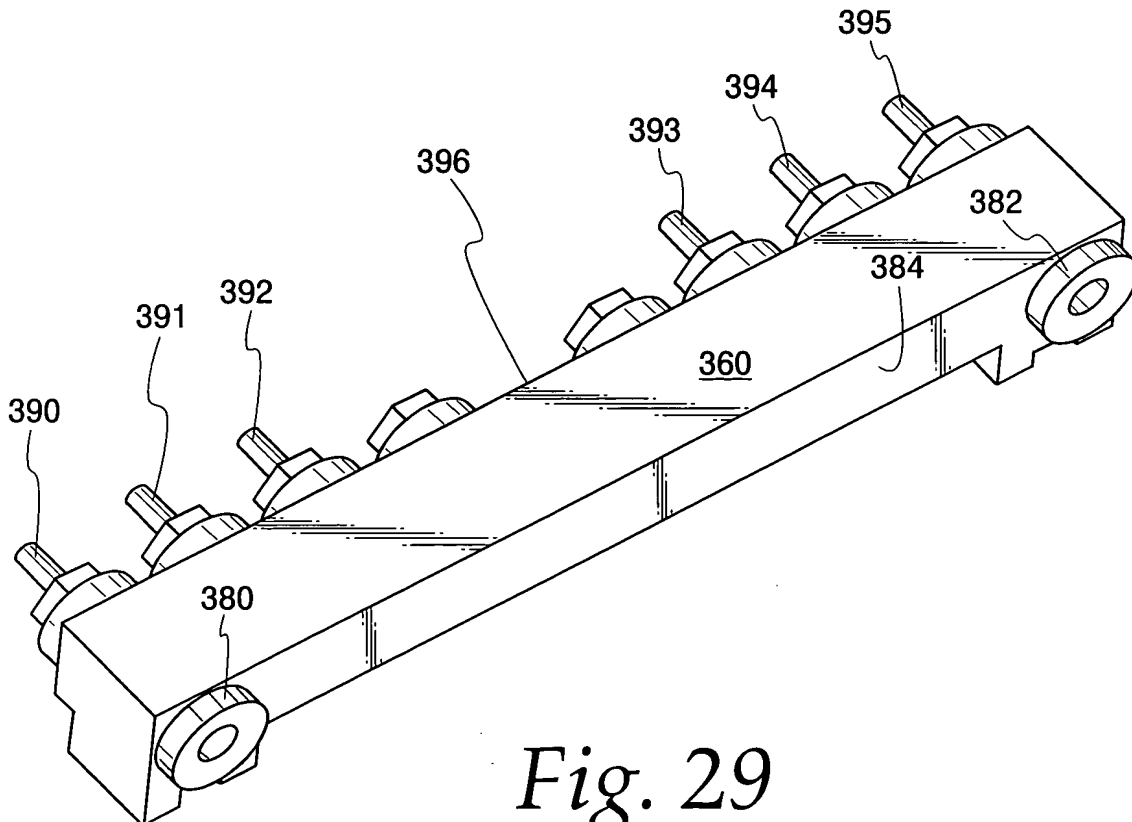
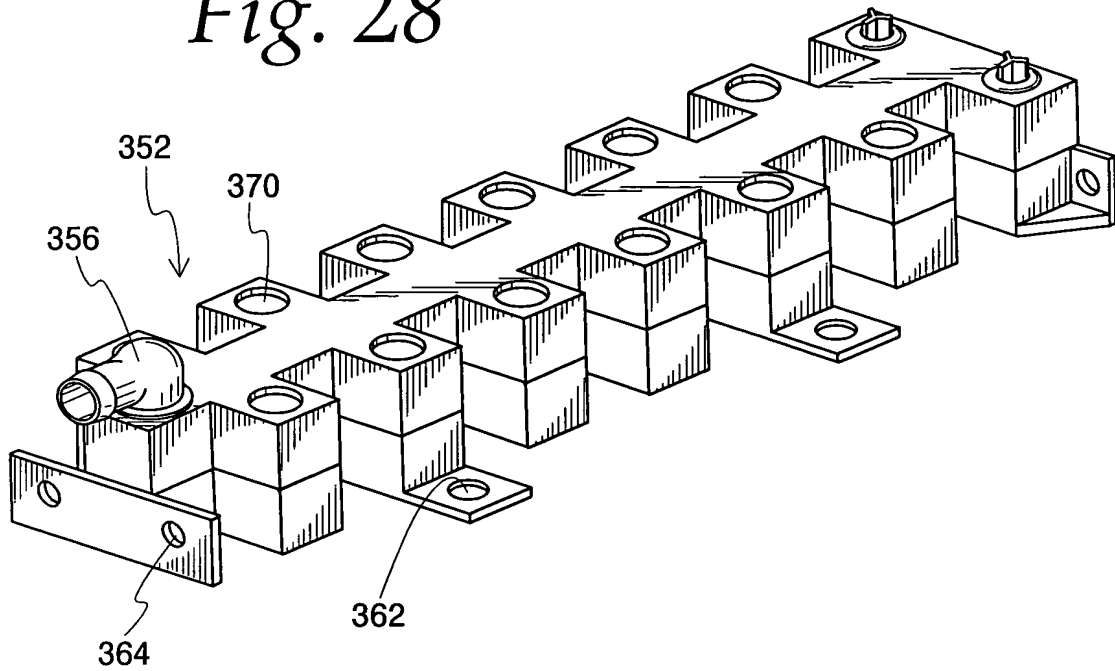
*Fig. 25*





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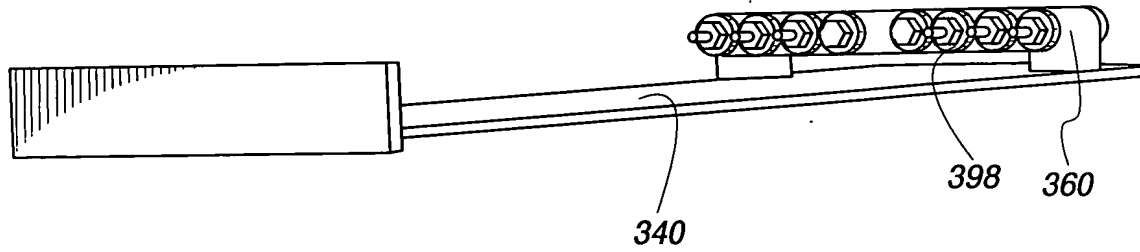
*Fig. 28*



*Fig. 29*

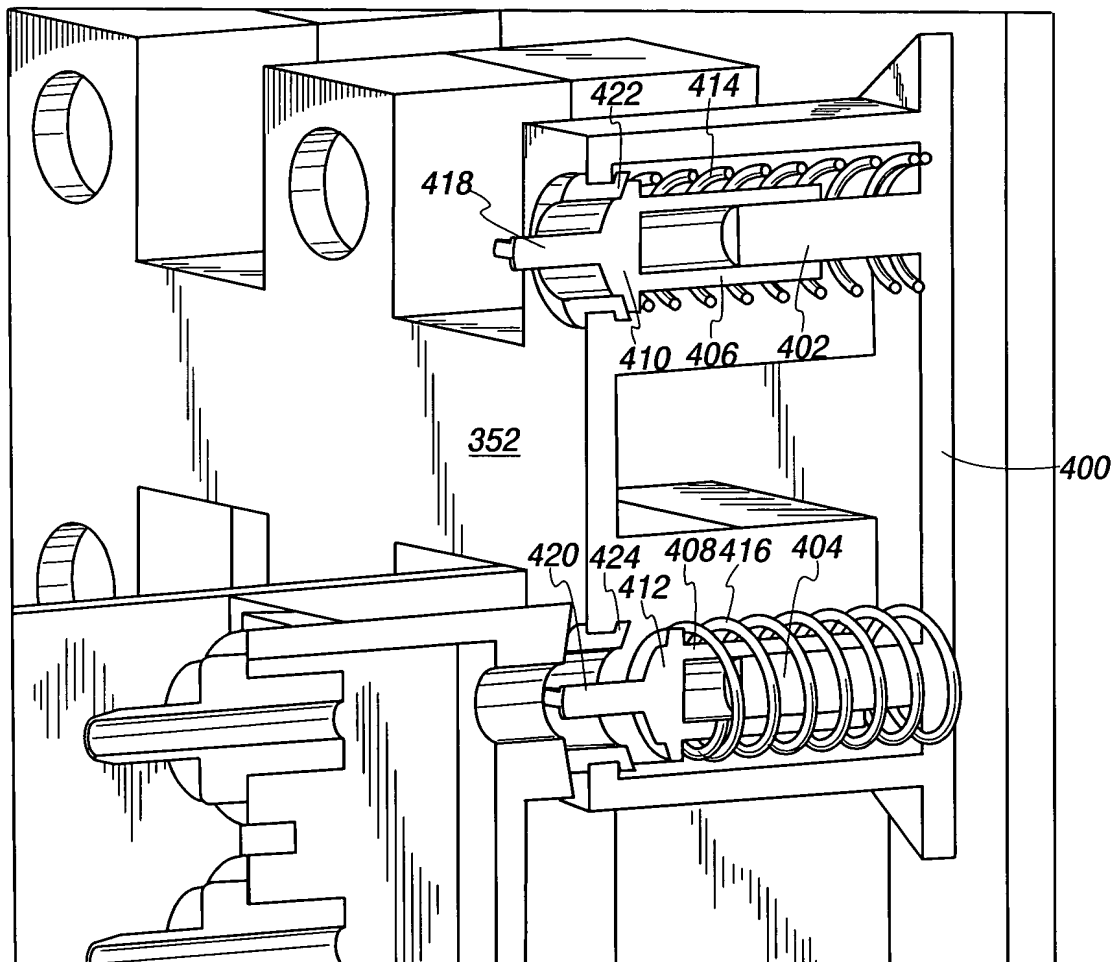
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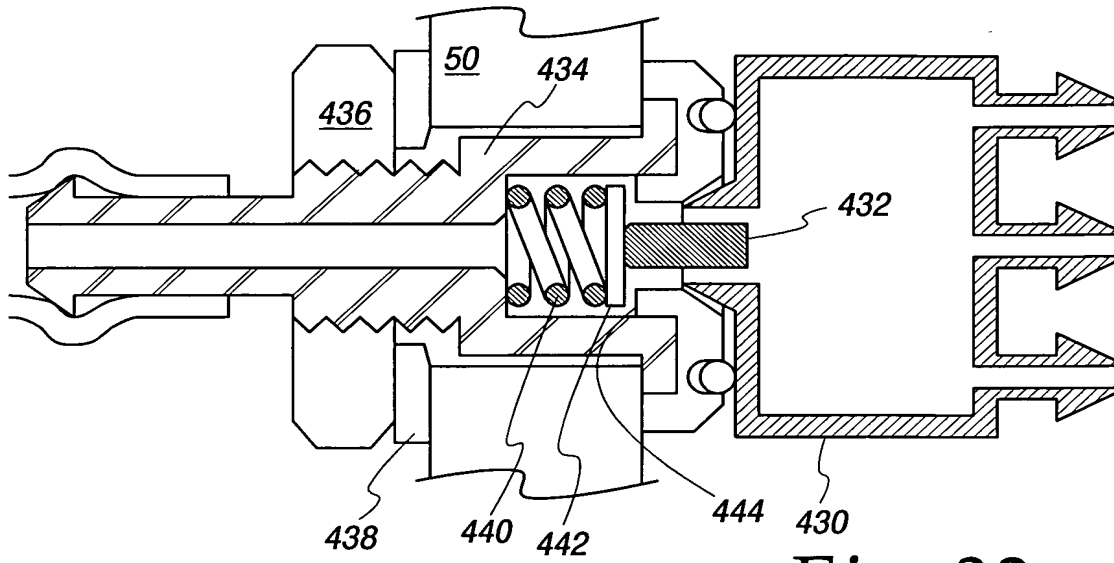
*Fig. 30*

*Fig. 31*

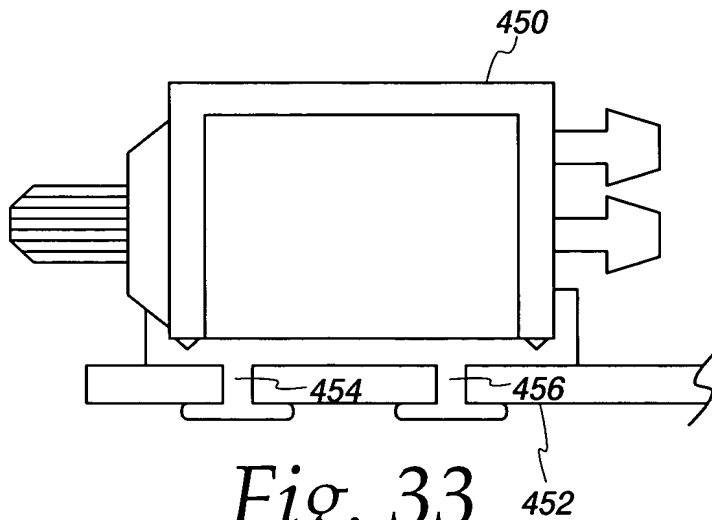


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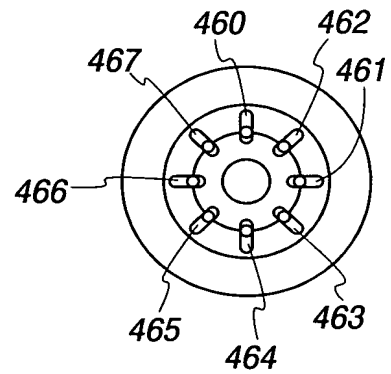
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*Fig. 32*



*Fig. 33*



*Fig. 34*



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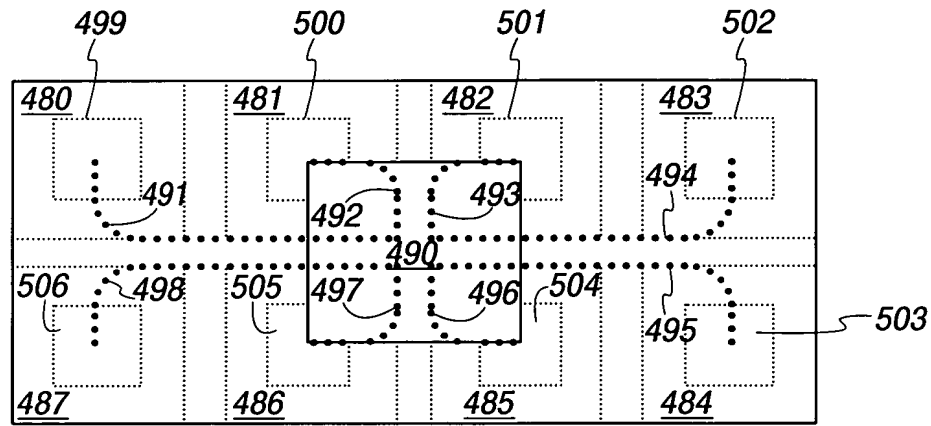


Fig. 35

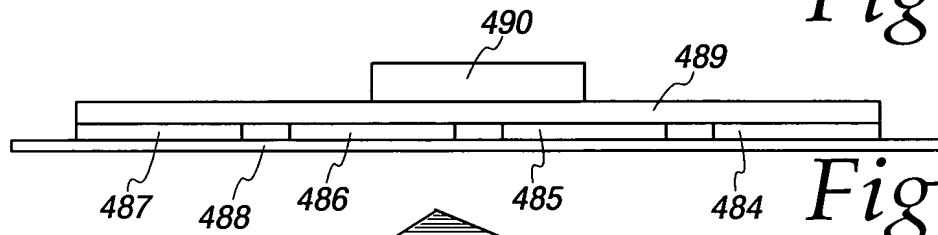


Fig. 36

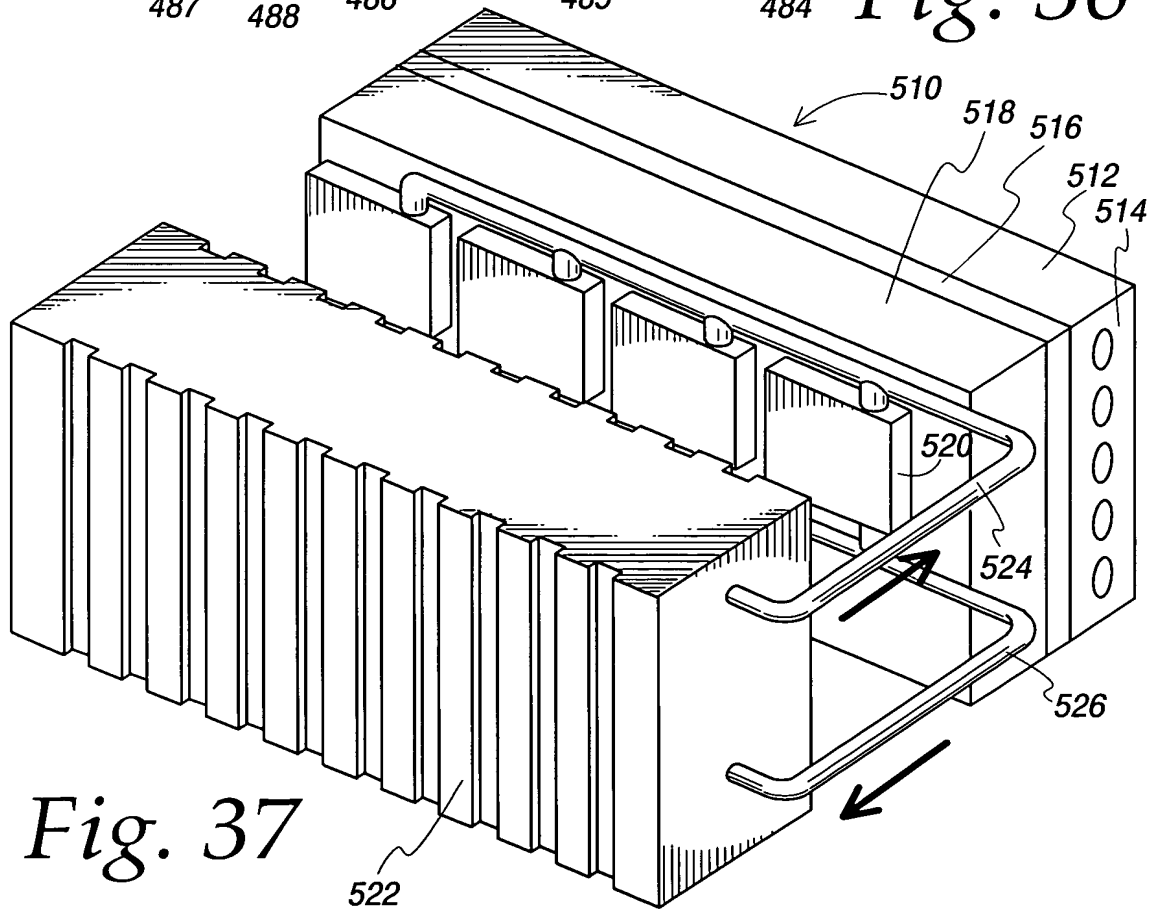


Fig. 37